

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No.	: 10/809,182	Confirmation No. 6820
Applicant(s)	: UMENO, Kuniharu et al.	
Filed	: 03/25/2004	
TC/A.U.	: 1712	
Examiner	: Robert E. Sellers	
Title	: Resin Composition for Encapsulating Semiconductor Chip and Semiconductor Device Therewith	

Docket No. : 033036.076
Customer No. : 25461

MAIL STOP AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450
Sir:

AMENDMENT

In response to the Office Action of April 16, 2007, please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 5 of this paper.